

ELP 38/8/25 with I 38/4/25 Cores (with and without clamp recess)

Series/Type: B66289G, B66289K, B66459G, B66459K

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ELP 38/8/25

Core (with clamp recess)

B66289

Core set EELP 38

Combination: ELP 38/8/25 with ELP 38/8/25

■ To IEC 62317-9

■ Delivery mode: single units

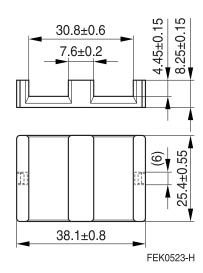
Magnetic characteristics (per set)

 $\Sigma I/A = 0.27 \text{ mm}^{-1}$ = 52.4 mm $= 194 \text{ mm}^2$ $A_{min} = 192 \text{ mm}^2$

 $V_e = 10200 \text{ mm}^3$

Approx. weight 52 g/set

Ungapped



ELP 38/8/25

Material	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code (per piece)
N49	4850 ±25%	1040	250	< 2.60 (50 mT, 500 kHz, 100 °C)	B66289G0000X149
N92	5400 ±25%	1160	350	< 6.65 (200 mT, 100 kHz, 100 °C)	B66289G0000X192
N87	7200 ±25%	1550	300	< 6.05 (200 mT, 100 kHz, 100 °C)	B66289G0000X187
N97	7400 ±25%	1590	310	< 5.15 (200 mT, 100 kHz, 100 °C)	B66289G0000X197

^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

Gapped (A_L values/air gaps examples)

Material	g mm	A _L value approx. nH	μ_{e}	Ordering code
N87	0.12 ±0.02	1700	370	B66289G0120X187
	0.60 ±0.05	400	90	B66289G0600X187

Other A_L values/air gaps and materials available on request – see Processing remarks on page 6.

Calculation factors (for formulas, see "E cores: general information") **EELP 38:**

Material	Relationship between air gap – A _L value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	302	-0.815	522	-0.796	466	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: $180 \text{ nH} < A_L < 1500 \text{ nH}$



ELP 38/8/25 with I 38/4/25

Core (with clamp recess)

B66289

138/4/25

Core set EILP 38 Combination:

ELP 38/8/25 with I 38/4/25

- To IEC 62317-9
- Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 0.22 \text{ mm}^{-1}$ = 43.6 mm $A_e = 194 \text{ mm}^2$ $A_{min} = 192 \text{ mm}^2$ $V_e = 8460 \text{ mm}^3$

Approx. weight 44 g/set

4.45±0.15 8.25±0.15 30.8±0.6 7.6±0.2 38.1±0.8 38.1±0.8 FEK0524-Q FEK0541-F

Ungapped

Mate- rial	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code (per piece)
N49	5700 ±25%	1000	250	< 2.20 (50 mT, 500 kHz, 100 °C)	B66289G0000X149 (ELP core) B66289K0000X149 (I core)**
N92	6200 ±25%	1110	350	< 5.30 (200 mT, 100 kHz, 100 °C)	B66289G0000X192 (ELP core) B66289K0000X192 (I core)**
N87	8300 ±25%	1450	300	< 5.15 (200 mT, 100 kHz, 100 °C)	B66289G0000X187 (ELP core) B66289K0000X187 (I core)**
N97	8400 ±25%	1500	310	< 4.40 (200 mT, 100 kHz, 100 °C)	B66289G0000X197 (ELP core) B66289K0000X197 (I core)**

ELP 38/8/25

Other A₁ values/air gaps and materials available on request – see Processing remarks on page 6.

Calculation factors (for formulas, see "E cores: general information") **EILP 38:**

Material	Relationship air gap – A _L v		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	328	-0.788	541	-0.796	477	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: $180 \text{ nH} < A_L < 1500 \text{ nH}$

^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

^{**} Plate-type tool



ELP 38/8/25

Core (without clamp recess)

B66459

Core set EELP 38

Combination: ELP 38/8/25 with ELP 38/8/25

■ To IEC 62317-9

■ Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 0.27 \text{ mm}^{-1}$ = 52.4 mm $= 194 \text{ mm}^2$

 $A_{min} = 192 \text{ mm}^2$ $V_e = 10200 \text{ mm}^3$

Approx. weight 52 g/set

30.8±0.6 7.6±0.2 25.4 ± 0.55 38.1±0.8 FEK0406-L

ELP 38/8/25

Ungapped

Material	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code (per piece)
N49	4850 ±25%	1040	250	< 2.60 (50 mT, 500 kHz, 100 °C)	B66459G0000X149
N92	5400 ±25%	1160	350	< 6.65 (200 mT, 100 kHz, 100 °C)	B66459G0000X192
N87	7200 ±25%	1550	300	< 6.05 (200 mT, 100 kHz, 100 °C)	B66459G0000X187
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Calculation factors (for formulas, see "E cores: general information") **EELP 38:**

Material	Relationship between air gap – A _L value		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	302	-0.815	522	-0.796	466	-0.873	

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K3, K4: $180 \text{ nH} < A_1 < 1500 \text{ nH}$



ELP 38/8/25 with I 38/4/25

Core (without clamp recess)

B66459

Core set EILP 38 Combination:

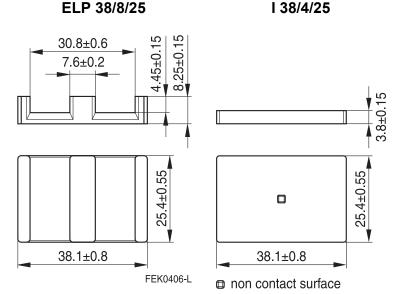
ELP 38/8/25 with I 38/4/25

- To IEC 62317-9
- Delivery mode: single units

Magnetic **characteristics** (per set)

 $\Sigma I/A = 0.22 \text{ mm}^{-1}$ = 43.6 mm $A_e = 194 \text{ mm}^2$ $A_{min} = 192 \text{ mm}^2$ $V_e = 8440 \text{ mm}^3$

Approx. weight 44 g/set



FEK0542-N-E

Ungapped

Mate- rial	A _L value nH	μ_{e}	B _S * mT	P _V W/set	Ordering code (per piece)
N49	5700 ±25%	1000	250	< 2.20 (50 mT, 500 kHz, 100 °C)	B66459G0000X149 (ELP core) B66459K0000X149 (I core)**
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^{*} H = 250 A/m; f = 10 kHz; T = 100 °C

Other A_I values/air gaps and materials available on request – see Processing remarks on page 6.

Calculation factors (for formulas, see "E cores: general information") **EILP 38:**

Material	Relationship air gap – A _L v		Calculation of saturation current				
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)	
N87	328	-0.788	541	-0.796	477	-0.873	

Validity range: K1, K2: 0.10 mm < s < 2.00 mm

K3, K4: $180 \text{ nH} < A_L < 1500 \text{ nH}$

^{**} Plate-type tool



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on A_I value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

EPCOS ferrite accessories have been designed and evaluated only in combination with EPCOS ferrite cores. EPCOS explicitly points out that EPCOS ferrite accessories or EPCOS ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

EPCOS assumes no warranty or reliability for the combination of EPCOS ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the customers' drilling process must be considered by increasing the hole diameter.

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Cautions and warnings

Display of ordering codes for EPCOS products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_{L}	Inductance factor; $A_L = L/N^2$	nH
A_{L1}	Minimum inductance at defined high saturation ($\stackrel{\triangle}{=} \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A_N	Winding cross section	mm ²
A_R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega = 10^{-6} \Omega$
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔB	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
ΔÂ	Peak value of flux density deviation	Vs/m ² , mT
B_DC	DC magnetic flux density	Vs/m ² , mT
B_R	Remanent flux density	Vs/m ² , mT
B_S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
E_a	Activation energy	J
f	Frequency	s ^{−1} , Hz
f _{cutoff}	Cut-off frequency	s−1, Hz
f _{max}	Upper frequency limit	s ^{−1} , Hz
f _{min}	Lower frequency limit	s−1, Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_{Cu}	Copper filling factor	
g	Air gap	mm
Н	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ⁻⁶ cm/A
h/μ_i^2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
1	RMS value of current	Α
I_{DC}	Direct current	Α
î	Peak value of current	Α
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k_3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
Δ L/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L_H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L_s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P_{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = ω L/R _s = 1/tan δ _L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R_i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
T	Temperature	°C
ΔT	Temperature difference	K
T_C	Curie temperature	°C
t	Time	S
t_{v}	Pulse duty factor	
$tan \ \delta$	Loss factor	
tan δ_{L}	Loss factor of coil	
tan δ_r	(Residual) loss factor at H $ ightarrow$ 0	
tan δ_{e}	Relative loss factor	
tan δ_{h}	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V_{e}	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z /N^2 \times \varepsilon (l_e/A_e)$	Ω/mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
ϵ_{r}	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η_{B}	Hysteresis material constant	mT-1
η _i	Hysteresis core constant	$A^{-1}H^{-1/2}$
λ_{S}	Magnetostriction at saturation magnetization	
u	Relative complex permeability	
ι_0	Magnetic field constant	Vs/Am
ι_{a}	Relative amplitude permeability	
^l app	Relative apparent permeability	
μ_{e}	Relative effective permeability	
l _i	Relative initial permeability	
ι_{p}'	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
ι μ <mark>p</mark> "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
ι_{r}	Relative permeability	
\mathfrak{u}_{rev}	Relative reversible permeability	
ι _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
ι _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
ι_{tot}	Relative total permeability	
	derived from the static magnetization curve	
)	Resistivity	Ω m $^{-1}$
ΣΙ/Α	Magnetic form factor	mm ⁻¹
^t Cu	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; ω = 2 Π f	s ⁻¹

All dimensions are given in mm.





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